IEEE P802.11
Wireless LANs

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| TGbe July 06 2022 Teleconference Minutes |
| Date: 2022-07-06 |
| Author(s): |
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Abstract

This document contains the minutes for the July 06 2022 IEEE 802.11 TGbe teleconference.

Revision history:

* Rev0: First version of the document.
* Rev1: Added the participant list for the July 6th meeting.

# Wednesday, July 06, Joint (07:00-09:00)

1. The Chair, Alfred Asterjadhi (Qualcomm), calls the meeting to order at 07:00 ET. The Chair notifies the attendees that the agenda is in [11-22-0974r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0974-00-00be-may-july-tgbe-teleconference-agenda.docx).
2. IEEE-SA Policies and Procedure

The chair reviews the IEEE-SA Patent Policy:

If anyone in this meeting is personally aware of the holder of any patent claims that are potentially essential to implementation of the proposed standard(s) under consideration by this group and that are not already the subject of an Accepted Letter of Assurance, please respond at this time by providing relevant information to the WG Chair. Speak up now and respond to this Call for Potentially Essential Patents. **Nobody speaks/writes up**.

1. The chair goes through Other guidelines for IEEE WG meetings, Patent-related information, Participation in IEEE 802 Meetings, and Copyright. The Chair asks that it be minuted that the **Copyright Policy** was presented.
2. Chair provides an attendance reminder:

3.1. Please record your attendance during the conference call by using the IMAT system:

Ueo 1) login to imat, 2) select “802.11 Electronic Plenary(<Month>)” entry, 3) select “C/LM/WG802.11 Attendance” entry, 4) click “TGbe <MAC/PHY/Joint> conference call that you are attending.

* 1. If you are unable to record your attendance contact the Chair Alfred Asterjadhi for assistance
	2. Chair notes that the attendance server is currently down
		1. Jon Rosdahl says that he will attempt to restore the attendance server function. Participants in this call:
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1. Announcements:
	1. TGbe LB266 D2.0 has completed and failed with ~64% Approve
	2. No secretary has volunteered
2. Chair notes that attendance server is back up
3. Editor comments
	1. Note that nine 802.19 comments included in the TGbe comment spreadsheet
4. Agenda:
	1. Chair reviews proposed agenda
	2. Discussion:
* None
	1. Agenda approved with unanimous consent.
1. Editor’s report [11-22-0972r1](https://mentor.ieee.org/802.11/dcn/22/11-22-0972-01-00be-tgbe-editor-s-report-on-lb266.ppt)
	1. Editor reviews contents of the editor’s report document [11-22-0972r1](https://mentor.ieee.org/802.11/dcn/22/11-22-0972-01-00be-tgbe-editor-s-report-on-lb266.ppt)
	2. Editor has categorized the comments
	3. No questions for the editor
2. Hybrid meeting details
	1. Chair discusses TGbe meeting plan for the July Montreal meeting, see [11-22-0974r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0974-00-00be-may-july-tgbe-teleconference-agenda.docx)
3. Editor asks attendees to send emails to indicate specifically whether they will volunteer as POC (Point of Contact) or TTT participant for CIDs
	1. Discussion:
* C: Volunteers will be added to the spreadsheet?
* C: what will be added to the assignee column?
* A: POC, and additional volunteers in the notes column
* A: POC should send a list of CIDs to the editor
* A: best to indicate a subclause rather than a list of CIDs, this makes it easier to manage the database
* C: looking at 11-22-0971r0 – will each subclause have a POC?
* C: hope to complete joint CIDs today, remaining comments by the end of the week
* C: Need to upload document by Sunday, or just request by Sunday?
* A: only request by Sunday
1. LB266 Joint Comment assignments
	1. Editor presents the comment doc [11-22-0974r0](https://mentor.ieee.org/802.11/dcn/22/11-22-0974-00-00be-may-july-tgbe-teleconference-agenda.docx)
	2. Editor reviews subclauses that have comments, looking for volunteers for POC
2. CR Submissions:
	1. No time remaining in the call for CR submission presentations
3. AoB: No other business.
4. Recess at 09:00 ET